

Final Product Change Notification

201903002F01

Issue Date: 07-Apr-2019

Effective Date: 06-Jul-2019

Here's your personalized quality information concerning products Digi-Key purchased from Nexperia. For detailed information we invite you to view this notification online



Change Category

Wafer Fab Process

Wafer Fab Materials

Wafer Fab Location

Assembly Process

Assembly Materials

Assembly Location

Product Marking

Mechanical Specification

Packing/Shipping/Labeling

Test Location

Test Process

Test Equipment

Design

Errata

Electrical spec./Test coverage

Release of ATGD as assembly site for ESD protection devices in SOT1176

Details of this Change

Nexperia assembly site ATGD will be released for affected products. Additionally for one product, also wafer material will be transferred from 150 mm to 200 mm. Due to different assembly site, marking appearance and labels will differ from current products when devices were assembled in ATGD.

Following are the details:

- Current:

- + Mold compound supplier: Sumitomo
- + Lead frame material: NiPdAuAg
- + Assembly and final test center: UTAC/ATBK
- + Wafer diameter: 150mm for product IP4283CZ10-TBR only

- New (additional):

- + Mold compound supplier: Hitachi
- + Lead frame material: NiPdAu
- + Assembly and final test center: ATGD
- + Wafer diameter: 200mm for product IP4283CZ10-TBR only

Why do we Implement this Change

To achieve a higher supply capability for ESD protection devices in SOT1176 package, additional production capacity in ATGD will be introduced.

Identification of Affected Products

- side view of device
- top side marking of product

- reel
- label (e.g. country of origin)

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 15-Jul-2019

Impact

no impact to the product's functionality anticipated.

Disposition of Old Products

Since ATGD will be released additionally, old products will be shipped in parallel

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 07-May-2019. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

<<<<<<< PCN2.html

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We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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Nexperia B.V.

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Affected Part Numbers

| | |
|--------------------|--------------------|
| IP4294CZ10-TBR,115 | PUSB3F96X |
| IP4283CZ10-TBR,115 | PUSB3FA2Z |
| PUSB3FR4Z | PUSB3FA1Z |
| PUSB3AB4Z | IP4292CZ10-TBR,115 |
| PHDMI2FR4Z | PHDMI2F4X |
| PHDMI2AB4Z | |